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- Low-Cost Single-Channel High-Speed MOSFET Driver
- I_{CC} . . . 15-μA Max (TPS2828, TPS2829)
- 25-ns Max Rise/Fall Times and 40-ns Max Propagation Delay . . . 1-nF Load
- 2-A Peak Output Current
- 4-V to 14-V Driver Supply Voltage Range; Internal Regulator Extends Range to 40 V (TPS2816, TPS2817, TPS2818, TPS2819)
- 5-pin SOT-23 Package
- –40°C to 125°C Ambient-Temperature Operating Range
- Highly Resistant to Latch-ups

description

The TPS28xx single-channel high-speed MOSFET drivers are capable of delivering peak currents of up to 2 A into highly capacitive loads. High switching speeds (t_r and t_f = 14 ns typ) are obtained with the use of BiCMOS outputs. Typical threshold switching voltages are 2/3 and 1/3 of V_{CC} . The design inherently minimizes shoot-through current.

TPS2816, TPS2817 TPS2818, TPS2819 **DBV PACKAGE** (TOP VIEW) 5 V_{DD} VCC 2 **GND** OUT IN TPS2828, TPS2829 **DBV PACKAGE** (TOP VIEW) 5 VCC 2 GND

NC - No internal connection

OUT

3

IN

A regulator is provided on TPS2816 through TPS2819 devices to allow operation with supply inputs between 14 V and 40 V. The regulator output can be used to power other circuits, provided power dissipation does not exceed package limitations. If the regulator is not required, V_{DD} (the regulator input) should be connected to V_{CC} . The TPS2816 and TPS2817 input circuits include an active pullup circuit to eliminate the need for an external resistor when using open-collector PWM controllers. The TPS2818 and TPS2819 are identical to the TPS2816 and TPS2817, except that the active pullup circuit is omitted. The TPS2828 and TPS2829 are identical to the TPS2818 and TPS2819, except that the internal voltage regulator is omitted, allowing quiescent current to drop to less than 15 μ A when the inputs are high or low.

The TPS28xx series devices are available in 5-pin SOT-23 (DBV) packages and operate over an ambient temperature range of –40°C to 125°C.

AVAILABLE OPTIONS

_	FUNCTION	PACKAGED DEVICES	CHIP FORM	
TA	FUNCTION	SOT-23-5 (DBV)	(Y)	
	Inverting driver with active pullup input	TPS2816DBV	TPS2816Y	
	Noninverting driver with active pullup input	TPS2817DBV	TPS2817Y	
-40°C to 125°C	Inverting driver	TPS2818DBV	TPS2818Y	
-40 C to 125 C	Noninverting driver	TPS2819DBV	TPS2819Y	
	Inverting driver, no regulator	TPS2828DBV	TPS2828Y	
	Noninverting driver, no regulator	TPS2829DBV	TPS2829Y	

The DBV package is available taped and reeled only.

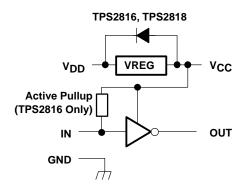


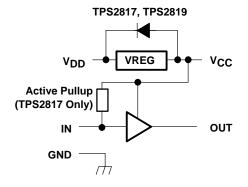
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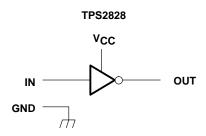


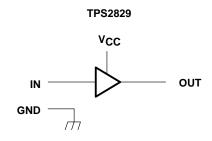
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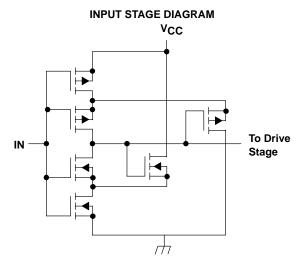
functional block diagram

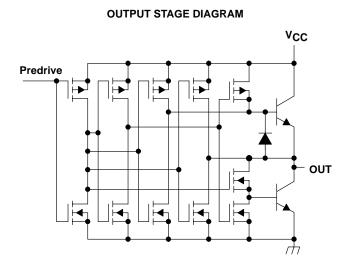






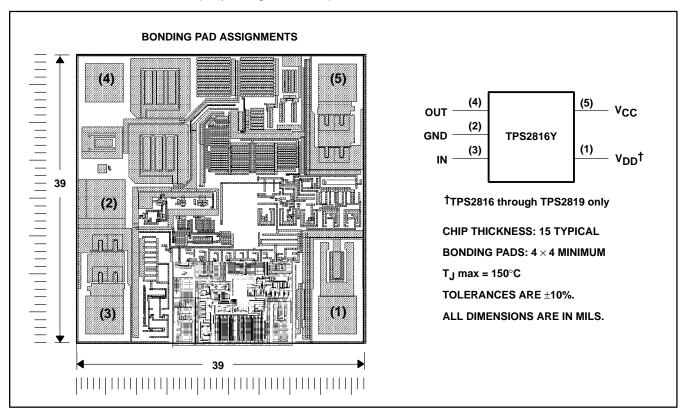






TPS28xxY chip information

This chip, when properly assembled, displays characteristics similar to those of the TPS28xx. Thermal compression or ultrasonic bonding may be used on the doped aluminum bonding pads. The chip may be mounted with conductive epoxy or a gold-silicon preform.



Terminal Functions

TPS2816, TPS2818, TPS2828 (inverting driver)

TERMINAL NO.		DESCRIPTION		
		DESCRIPTION		
V _{DD} 1 Regulator supply voltage input. (Not connected on TPS2828)		Regulator supply voltage input. (Not connected on TPS2828)		
GND	2	Ground		
IN 3		Driver input.		
OUT	4	Driver output, OUT = IN		
V _{CC} 5 Driver supply voltage/regulator output voltage		Driver supply voltage/regulator output voltage		

TPS2817, TPS2819, TPS2829 (noninverting driver)

TERMINAL		DECODIPTION	
NAME	NO.	DESCRIPTION	
V_{DD}	1	Regulator supply voltage input. (Not connected on TPS2829)	
GND	2	Ground	
IN	3	river input.	
OUT	4	Driver output, OUT= IN	
Vcc	5	Driver supply voltage/regulator output voltage	



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DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 80°C POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

These dissipation ratings are based upon EIA specification JESD51-3, "Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages," in tests conducted in a zero-airflow, wind tunnel environment.

absolute maximum ratings over operating temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.3 V to 15 V
Regulator supply voltage range, V _{DD}	V _{CC} –0.3 V to 42 V
Input voltage range, IN	0.3 V to V _{CC} +0.5 V
Output voltage range, (pin 4)	0.5 V to V _{CC} +0.5 V
Continuous regulator output current, V _{CC}	
Continuous output current, OUT	±100 mA
Continuous total power dissipation	. See Dissipation Rating Table
Operating ambient temperature range, T _A	–40°C to 125°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to device GND terminal.

recommended operating conditions

	MIN	MAX	UNIT
Regulator input voltage range, V _{DD} , TPS2816 through TPS2819	8	40	V
Supply voltage, V _{CC}	4	14	V
Input voltage, IN	-0.3	VCC	V
Continuous regulator output current, I _{CC}	0	20	mA
Operating ambient temperature range, TA	-40	125	°C



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TPS28xx electrical characteristics over recommended operating ambient temperature range, V_{CC} = 10 V, V_{DD} tied to V_{CC} , C_L = 1 nF (unless otherwise specified)

Inputs

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
	V _{CC} = 5 V		3.3	4	
Positive-going input threshold voltage	V _{CC} = 10 V		6.6	7	V
	V _{CC} = 14 V		9.3	10	
Negative-going input threshold voltage	V _{CC} = 5 V	1	1.7		
	V _{CC} = 10 V	2	3.3		V
	V _{CC} = 14 V	2.5	4.6		
Input voltage hysteresis			1.3		V
Input current, TPS2818/19/28/29	Input = 0 V or V _{CC}		0.2		μΑ
Local Comment TD00040/47	Input = 0 V		650		
Input current, TPS2816/17	Input = V _{CC}		15		μΑ
Input capacitance			5	10	pF

[†] Typicals are for $T_A = 25^{\circ}$ C unless otherwise noted.

outputs

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
	$I_O = -1 \text{ mA}$	9.75	9.9		
High-level output voltage	$I_{O} = -100 \text{ mA}$	8	9.1		V
Laur laural autout valta va	I _O = 1 mA		0.18	0.25	.,
Low-level output voltage	I _O = 100 mA		1	2	V

[†] Typicals are for $T_A = 25^{\circ}C$ unless otherwise noted.

regulator, TPS2816 through TPS2819

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Output voltage	$14 \le V_{DD} \le 40 \text{ V},$ $0 \le I_O \le 20 \text{ mA}$	10	11.5	13	٧
Output voltage in dropout	I _O = 10 mA, V _{DD} = 10 V	8		10	٧

 $^{^{\}dagger}$ Typicals are for TA = 25°C unless otherwise noted.

supply current

PARAMETER		TEST CONDITIONS	MIN TYP	MAX	UNIT
Supply current into V _{CC}	TPS2816,	IN = high = 10 V	150	250	
	TPS2817	IN = low = 0 V	650	1000	
	TPS2818, TPS2819		25	5 50	μА
	,		0.1	15]
Supply current into V _{DD}	TPS2816, TPS2817	V _{DD} = 20 V, IN = high = 10 V or low = 0 V	650	1000	
	TPS2818, TPS2819	V _{DD} = 20 V, IN = high = 10 V or low = 0 V	50	150	μΑ

[†] Typicals are for $T_A = 25^{\circ}C$ unless otherwise noted.



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TPS28xxY electrical characteristics at T_A = 25°C, V_{CC} = 10 V, V_{DD} tied to V_{CC} , C_L = 1 nF (unless otherwise specified)

Inputs

PARAMETER	TEST CONDITIONS	MIN TYP MAX	UNIT
	V _{CC} = 5 V	3.3	
Positive-going input threshold voltage	V _{CC} = 10 V	6.6	V
	V _{CC} = 14 V	9.3	
	V _{CC} = 5 V	1.7	
Negative-going input threshold voltage	V _{CC} = 10 V	3.3	V
	V _{CC} = 14 V	4.6	
Input voltage hysteresis		1.3	V
Input current, TPS2818/19/28/29	Input = 0 V or V _{CC}	0.2	μΑ
Level served TD00040/47	Input = 0 V	650	
Input current, TPS2816/17	Input = V _{CC}	15	μΑ
Input resistance		1000	МΩ
Input capacitance		5	pF

outputs

PARAMETER	TEST CONDITIONS	MIN TYP MAX	UNIT
	$I_O = -1 \text{ mA}$	9.9	
High-level output voltage	I _O = -100 mA	9.1	7 V
	I _O = 1 mA	0.18	
Low-level output voltage	I _O = 100 mA	1	7 V

regulator, TPS2816 through TPS2819

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output voltage	$14 \le V_{DD} \le 40 \text{ V},$ $0 \le I_O \le 20 \text{ mA}$		11.5		V
Output voltage in dropout	$I_{O} = 10 \text{ mA},$ $V_{DD} = 10 \text{ V}$		9		V

supply current

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
	TPS2816,	IN = high = 10 V	150			
	TPS2817	IN = low = 0 V		650		
Supply current into V _{CC}	TPS2818, TPS2819	IN = high or low,	25		μΑ	
	TPS2828, TPS2829	High = 10 V, Low = 0 V		0.1		
Supply current into V _{DD}	TPS2816, TPS2817	V _{DD} = 20 V, IN = high = 10 V or low = 0 V		650		4
Зарріу сапені нію УДД	TPS2818, TPS2819	$V_{DD} = 20 \text{ V},$ IN = high = 10 V or low = 0 V		50		μΑ



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switching characteristics for all devices over recommended operating ambient temperature range, $V_{CC} = 10 \text{ V}$, V_{DD} tied to V_{CC} , $C_L = 1 \text{ nF}$ (unless otherwise specified)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		V _{CC} = 14 V			25	
t _r	Rise time	V _{CC} = 10 V		14	30	ns
		V _{CC} = 5 V			35	
		V _{CC} = 14 V			25	
tf	Fall time	V _{CC} = 10 V		14	30	ns
		V _{CC} = 5 V			35	
		V _{CC} = 14 V			40	
tPHL	Propagation delay time, high-to-low-level output	V _{CC} = 10 V		24	45	ns
		V _{CC} = 5 V			50	
		V _{CC} = 14 V			40	
^t PLH	Propagation delay time, low-to-high-level output	V _{CC} = 10 V		24	45	ns
		V _{CC} = 5 V			50	

PARAMETER MEASUREMENT INFORMATION

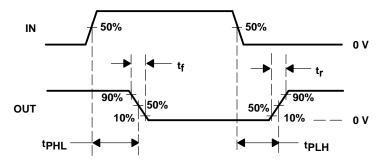


Figure 1. Typical Timing Diagram (TPS2816)

PARAMETER MEASUREMENT INFORMATION

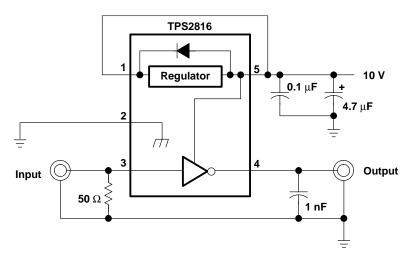


Figure 2. Switching Time Test Setup

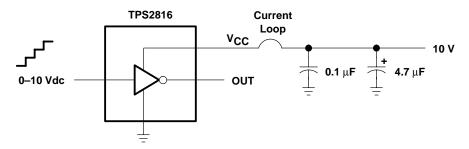


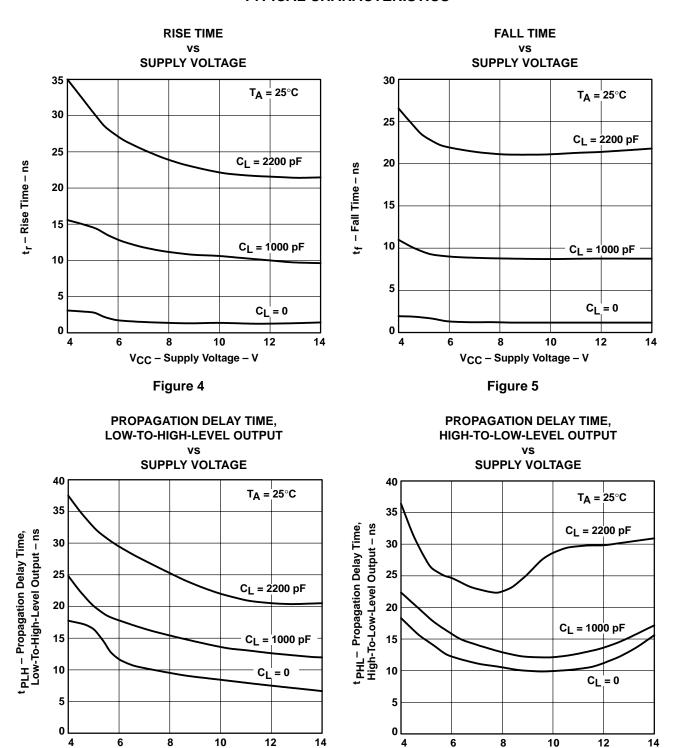
Figure 3. Shoot-Through Current Test Setup

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TYPICAL CHARACTERISTICS

Table of Graphs

		FIGURE
Rise time	vs Supply voltage	4
Fall time	vs Supply voltage	5
Propagation time (L>H)	vs Supply voltage	6
Propagation Time (H>L)	vs Supply voltage	7
Rise time	vs Ambient temperature	8
Fall time	vs Ambient temperature	9
Propagation time (L>H)	vs Supply voltage	10
Propagation time (H>L)	vs Ambient temperature	11
Supply current (V _{CC})	vs Supply voltage	12
Supply current (VCC)	vs Load capacitance	13
Supply current (V _{CC})	vs Ambient temperature	14
Input threshold voltage	vs Supply voltage	15
Regulator output voltage	vs Regulator supply voltage	16
Regulator quiescent current	vs Regulator supply voltage	17
Shoot-through current	vs Input voltage (L>H)	18
Shoot-through current	vs Input voltage (H>L)	19



V_{CC} - Supply Voltage - V

Figure 7

V_{CC} - Supply Voltage - V

Figure 6

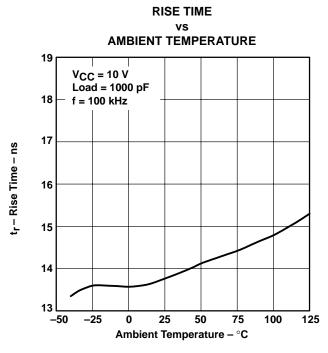
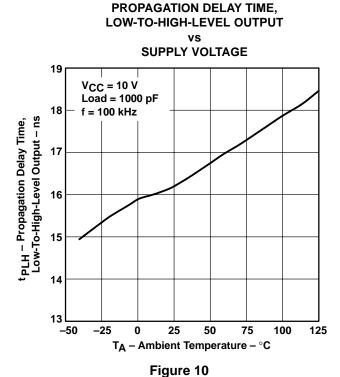


Figure 8



FALL TIME

VS

AMBIENT TEMPERATURE

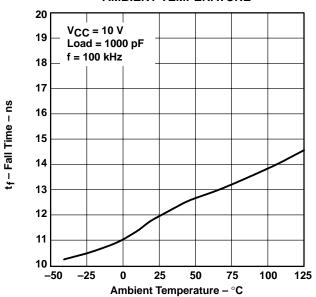


Figure 9

PROPAGATION DELAY TIME, HIGH-TO-LOW-LEVEL OUTPUT

AMBIENT TEMPERATURE

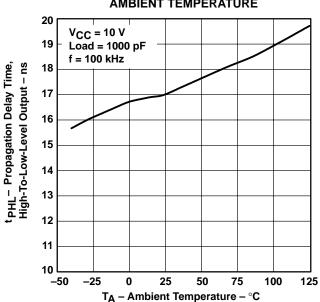
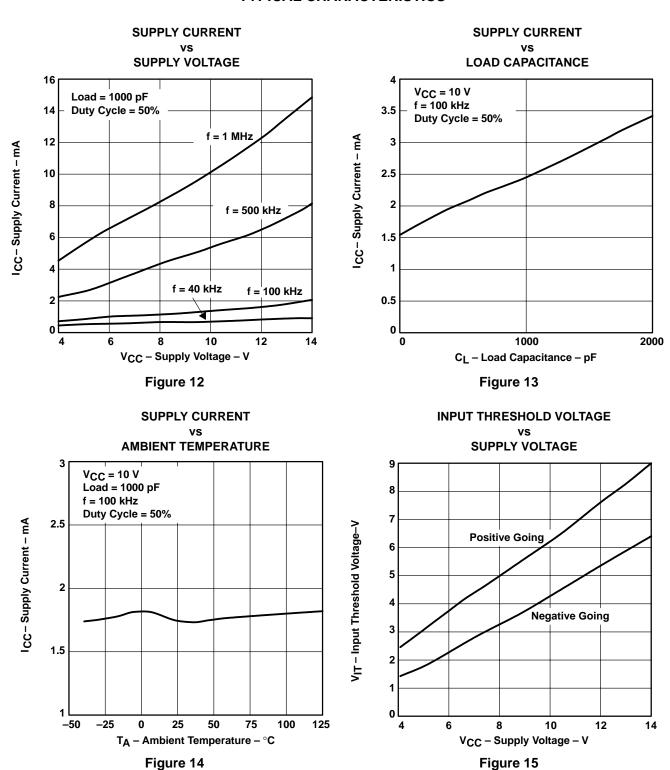


Figure 11



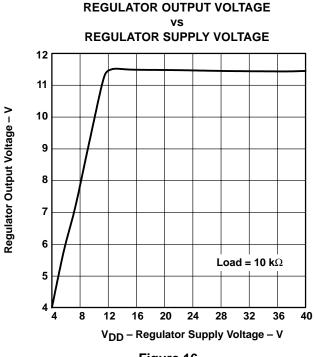
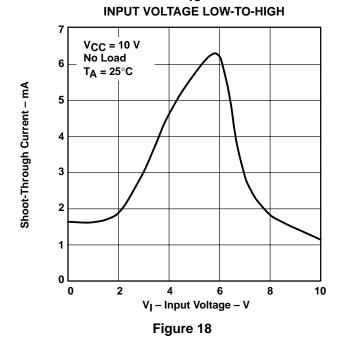
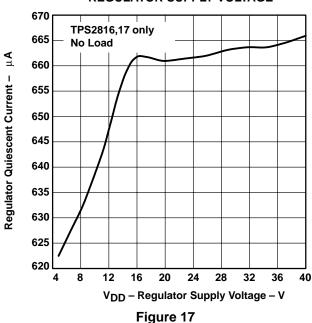


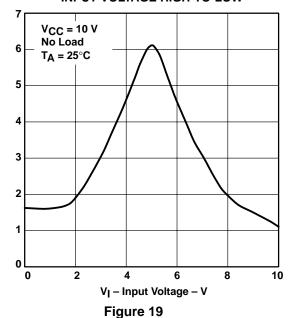
Figure 16
SHOOT-THROUGH CURRENT



REGULATOR QUIESCENT CURRENT vs REGULATOR SUPPLY VOLTAGE



SHOOT-THROUGH CURRENT vs INPUT VOLTAGE HIGH-TO-LOW



Shoot-Through Current – mA

MOSFETs are voltage-driven devices that require very little steady-state drive current. However, the large input capacitance (200 pF to 3000 pF or greater) of these devices requires large current surges to reduce the turn-on and turn-off times. The TPS2816 series of high-speed drivers can supply up to 2 A to a MOSFET, greatly reducing the switching times. The fast rise times and fall times and short propagation delays allow for operation in today's high-frequency switching converters.

In addition, MOSFETs have a limited gate-bias voltage range, usually less than 20 V. The TPS2816 series of drivers extends this operating range by incorporating an on-board series regulator with an input range up to 40 V. This regulator can be used to power the drivers, the PWM chip, and other circuitry, providing the power dissipation rating is not exceeded.

When using these devices, care should be exercised in the proper placement of the driver, the switching MOSFET, and the bypass capacitor. Because of the large input capacitance of the MOSFET, the driver should be placed close to the gate to eliminate the possibility of oscillations caused by trace inductance ringing with the gate capacitance of the MOSFET. When the driver output path is longer than approximately 2 inches, a resistor in the range of 10 Ω should be placed in series with the gate drive as close as possible to the MOSFET. A ceramic bypass capacitor is also recommended to provide a source for the high-speed current transients that the MOSFET requires. This capacitor should be placed between V_{CC} and GND of the driver (see Figures 20 and 21).

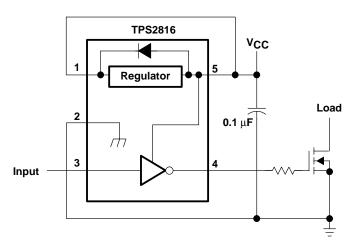


Figure 20. V_{CC} < 14 V

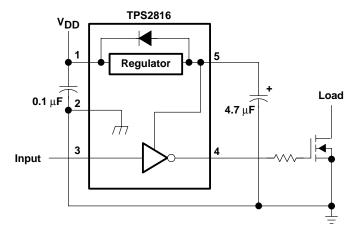


Figure 21. $V_{CC} > 14 \text{ V}$



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APPLICATION INFORMATION

The on-board series regulator supplies approximately 20 mA of current at 11.5 V, some of which can be used for external circuitry, providing the power dissipation rating for the driver is not exceeded. When using the on-board series regulator, an electrolytic output capacitor of 4.7 μF or larger is recommended. Although not required, a 0.1- μF ceramic capacitor on the input of the regulator can help suppress transient currents (see Figure 22). When not used, the regulator should be connected to V_{CC} . Grounding V_{DD} will result in destruction of the regulator.

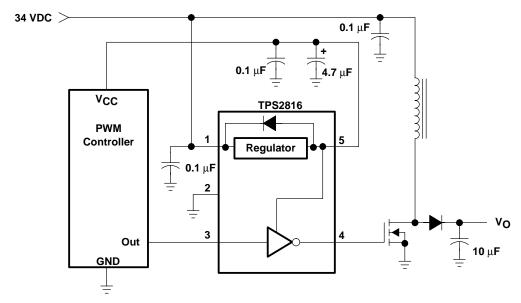


Figure 22. Boost Application

The TPS2816 and TPS2818 drivers include active pullup circuits on the inputs to eliminate the need for external pullup resistors when using controllers with open-collector outputs (such as the TL5001). The TPS2817 and TPS2819 drivers have standard CMOS inputs providing a total device operating current of less than 50 μ A. All devices switch at standard CMOS logic levels of approximately 2/3 V_{CC} with positive-going input levels, and approximately 1/3 V_{CC} with negative-going input levels. Being CMOS drivers, these devices will draw relatively large amounts of current (Approximately 5 mA) when the inputs are in the range of one-half of the supply voltage. In normal operation, the driver input is in this range for a very short time. Care should be taken to avoid use of very low slew-rate inputs, used under normal operating conditions. Although not destructive to the device, slew rates slower than 0.1 V/ μ s are not recommended.

The BiCMOS output stage provides high instantaneous drive current to rapidly toggle the power switch, and very low drop to each rail to ensure proper operation at voltage extremes.

Low-voltage circuits (less than 14 V) that require very low quiescent currents can use the TPS2828 and TPS2829 drivers. These drivers use typically $0.2~\mu\text{A}$ of quiescent current (with inputs high or low). They do not have the internal regulator or the active pullup circuit, but all other specifications are the same as for the rest of the family.

2.5-V/3.3-V, 3-A application

Figure 23 illustrates the use of the TPS2817 with a TL5001 PWM controller and a TPS1110 in a simple step-down converter application. The converter operates at 275 kHz and delivers either 2.5 V or 3.3 V (determined by the value of R6) at 3 A (5 A peak) from a 5-V supply. The bill of materials is provided in Table 1.

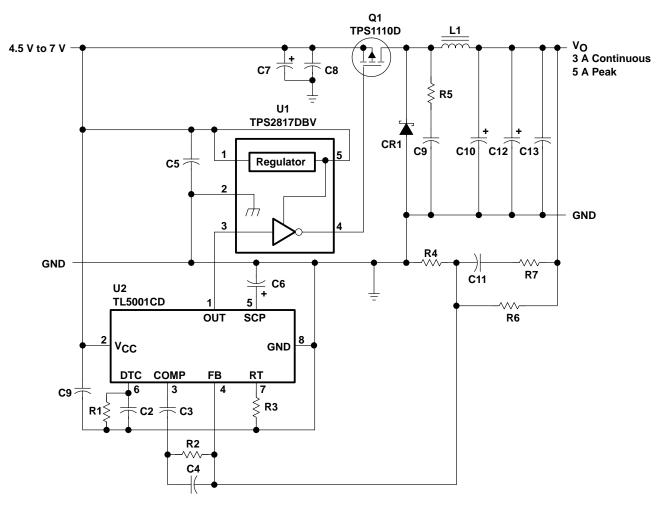


Figure 23. Step-Down Application

NOTE: If the parasitics of the external circuit cause the voltage to violate the Absolute Maximum Rating for the Output pins, Schottky diodes should be added from ground to output and from output to Vcc.

Table 1. Bill of Materials

REF DES	PART NO.	DESCRIPTION	MFR
U1	TPS2817DBV	IC, MOSFET driver, single noninverting	TI
U2	TL5001CD	IC, PWM controller	TI
Q1	TPS1110D	MOSFET, p-channel, 6 A, 7 V, 75 m Ω	TI
C1, C2, C5, C8		Capacitor, ceramic, 0.1 µF, 50 V, X7R, 1206	
C3		Capacitor, ceramic, 0.033 μF, 50 V, X7R, 1206	
C4		Capacitor, ceramic, 2200 pF, 50 V, X7R, 0805	
C6	ECS-T1CY105R	Capacitor, tantalum, 1.0 μF, 16 V, A case	Panasonic
C7	10SC47M	Capacitor, OS-Con, 47 μF, 10 V	Sanyo
C9		Capacitor, ceramic, 1000 pF, 50 V, X7R, 0805	
C10, C12	10SA220M	Capacitor, OS-Con, 220 μF, 10 V	Sanyo
C11		Capacitor, ceramic, 0.022 μF, 50 V, X7R, 0805	
C13		Capacitor, ceramic, 47 μF, 50 V, X7R	
CR1	50WQ03F	Diode, Shottky, D-pak, 5 A 30 V	IR
L1	SML3723	Inductor, 27 μH, +/- 20%, 3 A	Nova Magnetics
R1		Resistor, CF, 47 kΩ, 1/10 W, 5%, 0805	
R2		Resistor, CF, 1.5 kΩ, 1/10 W, 5%, 0805	
R3		Resistor, MF, 30.1 kΩ, 1/10 W, 1%, 0805	
R4		Resistor, MF, 1.00 kΩ, 1/10 W, 1%, 0805	
R5		Resistor, CF, 47 Ω, 1/10 W, 5%, 0805	
R6 (3.3-V)		Resistor, MF, 2.32 kΩ, 1/10 W, 1%, 0805	
R6 (2.5-V)		Resistor, MF, 1.50 kΩ, 1/10 W, 1%, 0805	
R7		Resistor, CF, 100 Ω, 1/10 W, 5%, 0805	

As shown in Figures 24 and 25, the TPS2817 turns on the TPS1110 power switch in less than 20 ns and off in 25 ns.

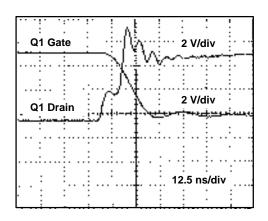


Figure 24. Q1 Turn-On Waveform

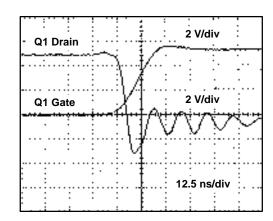


Figure 25. Q1 Turn-Off Waveform

The efficiency for various output currents, with a 5.25-V input, is shown in Figure 26. For a 3.3-V output, the efficiency is greater than 90% for loads up to 2 A – exceptional for a simple, inexpensive design.

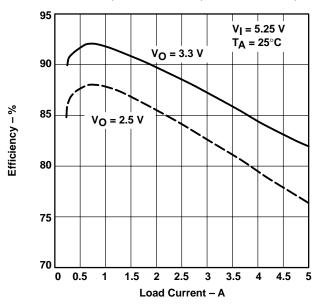


Figure 26. Converter Efficiency





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS2816DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAAI	Samples
TPS2816DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAAI	Samples
TPS2816DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAAI	Samples
TPS2816DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PAAI	Samples
TPS2817DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PABI	Samples
TPS2817DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PABI	Samples
TPS2817DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PABI	Samples
TPS2817DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PABI	Samples
TPS2818DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PACI	Samples
TPS2818DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PACI	Samples
TPS2819DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PADI	Samples
TPS2819DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PADI	Samples
TPS2819DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PADI	Samples
TPS2819DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PADI	Samples
TPS2828DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM		PAXI	Samples
TPS2828DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		PAXI	Samples
TPS2828DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		PAXI	Samples



PACKAGE OPTION ADDENDUM

17-Mar-2017

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS2828DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		PAXI	Samples
TPS2829DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	PAYI	Samples
TPS2829DBVRG4	ACTIVE	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 125	PAYI	Samples
TPS2829DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	PAYI	Samples
TPS2829DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	PAYI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

17-Mar-2017

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OTHER QUALIFIED VERSIONS OF TPS2816, TPS2817, TPS2818, TPS2819, TPS2828, TPS2829:

- Automotive: TPS2819-Q1, TPS2829-Q1
- Enhanced Product: TPS2816-EP, TPS2817-EP, TPS2818-EP, TPS2819-EP, TPS2828-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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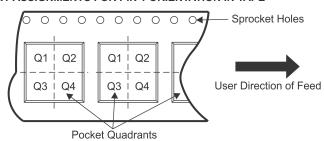
TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS2816DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2816DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2817DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2817DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2818DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2819DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2819DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2828DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS2828DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2828DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2829DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS2829DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS2816DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS2816DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS2817DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS2817DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS2818DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS2819DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS2819DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS2828DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS2828DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS2828DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS2829DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS2829DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0

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